

# **Smart Laser Processing Conference 2014**

## **SLPC2014**

**Tuesday, April 22**

**15:30-15:45 Opening**

Room 413

**Opening Remarks**

**15:30** Y. Okamoto, Okayama Univ., Japan

**15:45-17:30 SLPC1 : Advanced Lasers and Optical Technologies for Smart Processing** Room 413

**Chairs:** A. Ostendorf, Ruhr Univ., Germany,

S. Wada, RIKEN, Japan

**SLPC1-1 15:45 (Invited) Inline Coherent Imaging of Laser Materials Processing: Development, Diagnosis and Control**

P. J. L. Webster <sup>1,2)</sup>, C. V. Vlack <sup>1)</sup>, C. M. Galbraith <sup>2)</sup>, and J. M. Fraser <sup>2)</sup>

<sup>1)</sup> Laser Depth Dynamics Inc., Canada,

<sup>2)</sup> Queen's Univ., Canada

**SLPC1-2 16:15 A New 60 W 355 nm Laser for Precision Manufacturing**

R. Patel, J. Bovatsek, and A. Tamhankar

Spectra Physics, USA

**SLPC1-3 16:30 Laser Processing by Using Multi-level Free-form 3D Micro-fabricated DOE**

A. Hamano <sup>1)</sup>, A. Yamada <sup>1)</sup>, T. Takada <sup>2)</sup>, and Y. Usuki <sup>1)</sup>

<sup>1)</sup> Material Research Laboratory, R&D Division, Furukawa Co. Ltd., Japan,

<sup>2)</sup> R&D Planning Department, R&D Division, Furukawa Co. Ltd., Japan

**SLPC1-4 16:45 The Study of the Phase Difference of Beam Splitters Structure in the Fiber-optic Mach-Zehnder Interferometer**

J. T. Huang <sup>1)</sup>, C. H. Chen <sup>2)</sup>, C. T. Wang <sup>2)</sup>, and W. T. Wu <sup>1)</sup>

<sup>1)</sup> National Pingtung Univ. of Science and Technology, Taiwan, <sup>2)</sup>National Chung Cheng Univ., Taiwan

**SLPC1-5 17:00 Development of the Path Generation Algorithm for Large-area Laser Pattern Using the Manual Input Control Point**

K. Yoon, K. Kim, and J. Lee  
Korea Institute of Machinery and Materials, Korea

**SLPC1-6 17:15 Fiber-delivery and Compression of Milli-joule Femtosecond Pulses and Micromachining**

B. Debord <sup>1)</sup>, M. Dontabactouny <sup>1)</sup>, M. Alharbi <sup>1)</sup>, C. Fourcade-Dutin <sup>1)</sup>, C. Hönninger <sup>3)</sup>, E. Mottay <sup>3)</sup>, Q. Mocaer <sup>3)</sup>, L. Vincetti <sup>4)</sup>, F. Gerome <sup>1,2)</sup>, and F. Benabid <sup>1,2)</sup>

<sup>1)</sup> GPPMM Group, Xlim Research Institute, France, <sup>2)</sup> GLOphotonics S.A.S, France,

<sup>3)</sup> Amplitude Systèmes, France, <sup>4)</sup> Univ. of Modena and Reggio Emilia, Italy

**Wednesday, April 23**

**8:30-10:00 SLPC2: Short Wavelength Applications**

Room 313+314

**Chairs:** L. Li, The Univ. of Manchester, UK,

M. Katto, Univ. of Miyazaki, Japan

**SLPC2-1 8:30**

**(Invited) Update of EUV Source Development Status for HVM Lithography**

H. Mizoguchi <sup>1)</sup>, H. Nakurai <sup>1)</sup>, T. Abe <sup>1)</sup>, T. Ohta <sup>1)</sup>, K. M Nowak <sup>2)</sup>, Y. Kawasumi <sup>1)</sup>, H. Tanaka <sup>1)</sup>, Y. Watanabe <sup>1)</sup>, T. Hori <sup>1)</sup>, T. Kodama <sup>1)</sup>, Y. Shiraishi <sup>1)</sup>, T. Yanagida <sup>1)</sup>, T. Yamada <sup>1)</sup>, T. Yamazaki <sup>1)</sup>, S. Okazaki <sup>1)</sup>, and T. Saitou <sup>1)</sup>

<sup>1)</sup> Gigaphoton Inc., Oyama Facility, Japan,

<sup>2)</sup> Gigaphoton Inc., Hiratsuka Facility, Japan

**SLPC2-2 9:00 (Invited) Laser Induced Front Side Etching Using Excimer Laser**

Klaus Zimmer

Leibniz Institute of Surface Modification, Germany

**SLPC2-3 9:30 Straight Through Hole Drilling in Machinable Ceramics**

S. Nakamura <sup>1)</sup>, T. Miura <sup>2)</sup>, and M. Tsuta <sup>2)</sup>

<sup>1)</sup> Department of Electrical and Electronic Systems Engineering, Nagaoka National College of Technology, Japan, <sup>2)</sup> Electrical & Mechanical Systems Engineering Advanced Course, Nagaoka National College of Technology, Japan

**SLPC2-4 9:45 Improvement of Junction Properties of ZnO Nanowire / GaN Heterojunction Using Selective Laser Processing**

D. Nakamura, N. Tetsuyama, T. Shimogaki, M. Higashihata, and T. Okada  
Kyushu Univ., Japan

----- Break (10:00-10:30) -----

**10:30-11:45 SLPC3: Micro Nano Processing**

Room 313+314

**Chairs:** John Lopez, Univ. of Bordeaux, CNRS, France,

M. Fujita, Institute for Laser Technology, Japan

**SLPC3-1 10:30 (Invited) Laser Direct Writing of Graphene Patterns on Glasses under Ambient Condition**

Y. Lu <sup>1)</sup>, W. Xiong <sup>1)</sup>, W. J. Hou <sup>1)</sup>, L. J. Jiang <sup>1)</sup>, J. F. Silvain <sup>1,2)</sup>, and L. Jiang <sup>3)</sup>,

<sup>1)</sup> Univ. of Nebraska - Lincoln, USA,

<sup>2)</sup> Institut de Chimie de la Matière Condensée de Bordeaux (ICMCB), CNRS, France,

<sup>3)</sup> Beijing Institute of Technology, China

**SLPC3-2 11:00 (Invited) Ultrashort Pulsed Laser Processing: Laser Quantum Ejection from Transparent Thin Film and Their Promising Applications**

P. Herman <sup>1)</sup>, K. Kumar <sup>2)</sup>, K. K. C. Lee <sup>1)</sup>, J. Li <sup>1)</sup>, S. Ho <sup>1)</sup>, and J. Nogami <sup>2)</sup>

<sup>1)</sup> Department of Materials Science and Engineering, Univ. of Toronto, Canada,

<sup>2)</sup> Department of Electrical and Computer Engineering, Univ. of Toronto, Canada

**SLPC3-3 11:30 Laser Micromachining of Bio-absorbable Polymers: Impact of the Laser Process Parameters on the Machining Throughput and Quality**

F. Hendricks <sup>1)</sup>, R. Patel <sup>2)</sup>, and V. Matylitsky <sup>1)</sup>

<sup>1)</sup> High Q Laser, Newport Corp., Austria,

<sup>2)</sup> Spectra Physics, Newport Corp., USA

----- Lunch Break (11:45-12:30) -----

**12:30-14:15 SLPC4: Poster Session** Exhibition Hall C

**SLPC4p-1 All-fiber Microfluidic Mach-Zehnder Interferometer for Detection of Calcium**

	<b>Hydroxide</b> J. N. Wang <sup>1)</sup> , W. T. Wu <sup>2)</sup> , C. H. Chen <sup>3)</sup> , and P. L. Shen <sup>1)</sup> <sup>1)</sup> National Yunlin Univ. of Science and Technology, Taiwan, <sup>2)</sup> National Pingtung Univ. of Science and Technology, Taiwan, <sup>3)</sup> National Chung Cheng Univ., Taiwan	and M. Terakawa <sup>2)</sup> <sup>1)</sup> Department of Electronics and Electrical Engineering, Keio Univ., Japan, <sup>2)</sup> School of Integrated Design Engineering, Keio Univ., Japan
<b>SLPC4p-2</b>	<b>A Study of the Reflective Cladding-off Cylindrical Fiber Sensor</b> Y. T. Y. Kao, and W. T. Wu National Pingtung Univ. of Science and Technology, Taiwan	<b>Periodic Grating Structures on Metal Self-organized by Double Pulse Irradiations</b> L. Gemini <sup>1)</sup> , M. Hashida <sup>1)</sup> , T. Nishii <sup>1)</sup> , Y. Miyasaka <sup>1)</sup> , H. Sakagami <sup>2)</sup> , S. Inoue <sup>1)</sup> , and S. Sakabe <sup>1)</sup> <sup>1)</sup> Kyoto Univ., Japan, <sup>2)</sup> National Institute for Fusion Science, Japan
<b>SLPC4p-3</b>	<b>Method for Measuring of the Contrast of Multi-Beam-Interference with a Gaussian Beam-shape</b> M. Steger <sup>1,2)</sup> , S. Boes <sup>2)</sup> , S. Thilker <sup>2)</sup> , and A. Gillner <sup>2)</sup> <sup>1)</sup> Chair for Laser Technology, Technical Univ. Aachen, Germany, <sup>2)</sup> Fraunhofer Institute for Laser Technology, Germany	<b>Investigation of Micro-welding Characteristics of Si and Glass by Picosecond Pulsed Laser</b> I. H. W. Nordin <sup>1)</sup> , Y. Okamoto <sup>1)</sup> , I. Miyamoto <sup>2)</sup> , and A. Okada <sup>1)</sup> <sup>1)</sup> Okayama Univ., Japan, <sup>2)</sup> Osaka Univ., Japan
<b>SLPC4p-4</b>	<b>Holographic Vector Wave Femtosecond Laser Processing</b> S. Hasegawa, and Y. Hayasaki Center for Optical Research and Education (CORE), Utsunomiya Univ., Japan	<b>Thin Film CIGS Cell Scribing Using a High Energy Femtosecond Fiber Amplifier</b> F. Morin <sup>1)</sup> , Y. Zaouter <sup>1)</sup> , C. Hönninger <sup>1)</sup> , E. Mottay <sup>1)</sup> , Q. Mocaer <sup>1)</sup> , B. Dunne <sup>2)</sup> , R. D. Almeida <sup>3)</sup> , and J. P. Aguerre <sup>3)</sup> <sup>1)</sup> Amplitude Systèmes, France, <sup>2)</sup> NEXCIS Photovoltaic Technology, France, <sup>3)</sup> Mondragon Assembly, France
<b>SLPC4p-5</b>	<b>Solid-state-like Fiber Lasers: Ultrahigh Repetition Rate Femtosecond Fiber Laser and Applications</b> Z. Zhang, A. Wang, C. Li, X. Gao, G. Wang, and J. Zang Peking Univ., China	<b>Double-sided Laser-arc Hybrid Welding of High Strength Steel Thick Plate</b> L. Li, J. Feng, and Y. Chen Harbin Institute of Technology, China
<b>SLPC4p-6</b>	<b>Multifunctional Laser System for Micromachining of Various Materials</b> M. Milenky, E. V. Raevsky, and D. L. Saprykin Electronic Special Technological Equipment, Research & Development Institute, Russia	<b>Research Progress on the High Power Laser Processing Technique</b> L. Feng, and A. Wu Beijing Institute of Opto-Electronic Technology, China
<b>SLPC4p-7</b>	<b>Demonstration of Heat Resistant Bragg Grating by Femtosecond Laser Processing for Vibration Monitoring</b> A. Nishimura <sup>1)</sup> , Y. Takenaka <sup>2)</sup> , T. Furuyama <sup>2)</sup> , T. Shimomura <sup>3)</sup> , T. Terada <sup>3)</sup> , and H. Daido <sup>3)</sup> <sup>1)</sup> Japan Atomic Energy Agency, Kizugawa, Japan, <sup>2)</sup> A-Tech, Japan, <sup>3)</sup> Japan Atomic Energy Agency, Tsuruga, Japan	<b>Effects of Laser Peening Parameters on Plastic Deformation of Metallic Materials</b> M. Tsuyama <sup>1)</sup> , Y. Kodama <sup>2)</sup> , Y. Miyamoto <sup>2)</sup> , I. Kitawaki <sup>2)</sup> , T. Shibayanagi <sup>3)</sup> , M. Tsukamoto <sup>4)</sup> , and H. Nakano <sup>1)</sup> <sup>1)</sup> Faculty of Science and Engineering, Kinki Univ., Japan, <sup>2)</sup> Interdisciplinary Graduate School of Science and Engineering, Kinki Univ., Japan, <sup>3)</sup> Faculty of Engineering, Toyama Univ., Japan, <sup>4)</sup> Joining and Welding Research Institute, Osaka Univ., Japan
<b>SLPC4p-8</b>	<b>A Simplified Fabrication Technique for TFBG for the Simultaneous Measurement of Refractive Index and Temperature of Liquids</b> A. Kameyama <sup>1)</sup> , A. Yokotani <sup>1)</sup> , and M. Katto <sup>2)</sup> <sup>1)</sup> Faculty of Engineering, Univ. of Miyazaki, Japan, <sup>2)</sup> Center of Collaborative Research and Community Cooperation, Univ. of Miyazaki, Japan	<b>Experimental Study on CFRP Cutting with Nanosecond Laser in Air and Ar Gas Ambience</b> Y. Sato <sup>1)</sup> , M. Tsukamoto <sup>1)</sup> , F. Matsuoka <sup>2)</sup> , K. Takahashi <sup>1)</sup> , S. Masuno <sup>1)</sup> , T. Ohkubo <sup>3)</sup> , and H. Nakano <sup>2)</sup> <sup>1)</sup> Joining and Welding Research Institute, Osaka Univ., Japan, <sup>2)</sup> Department of Electrical Engineering, Kinki Univ., Japan, <sup>3)</sup> Department of Mechanical Science and Engineering, Tokyo Institute of Technology, Japan
<b>SLPC4p-9</b>	<b>The Absorption Property Change of Quartz in Micromachining by ns Pulsed CO<sub>2</sub> laser</b> K. Yamasaki, H. Ikenoue, Y. Watanabe, D. Nakamura, and T. Okada Kyushu Univ., Japan	----- Break (14:15-14:45) -----
<b>SLPC4p-10</b>	<b>Localized CO<sub>2</sub> Laser Smoothing of Defects on EUV Ti-doped Silica Substrates</b> A. Cournoyer, M. Briand, and Y. Duval INO, Canada	<b>14:45-16:00 SLPC5: Ultrashort Pulsed Laser Processing I</b> Room 313+314
<b>SLPC4p-11</b>	<b>Formation of Periodic Nanowire Array by Femtosecond Laser Irradiation</b> Y. Nakajima <sup>1)</sup> , H. Shimizu <sup>2)</sup> , T. Shinohara <sup>2)</sup> ,	<b>Chairs:</b> Y. Lu, Univ. of Nebraska-Lincoln, USA, M. Terakawa, Keio Univ., Japan
		<b>SLPC5-1 (Invited) Parameters of Influence in Surface Ablation and Texturing of Metals Using</b> 14:45

	<b>High-Power Ultrafast Laser</b> J. Lopez <sup>1)</sup> , M. Faucon <sup>2)</sup> , R. Devillard <sup>1)</sup> , Y. Zaouter <sup>3)</sup> , C. Hönninger <sup>3)</sup> , E. Mottay <sup>3)</sup> , and R. Kling <sup>2)</sup> <sup>1)</sup> Univ. of Bordeaux, CNRS, France, <sup>2)</sup> ALPHANOV, France, <sup>3)</sup> Amplitude Systèmes, France	9:30	<b>316 Stainless Steel Fabricated by Selective Laser Melting</b> H. Li, B. Huang, L. Ding, Y. Wang, and S. Gong Beijing Aeronautical Manufacturing Technology Research Institute, China
<b>SLPC5-2</b> <b>15:15</b>	<b>(Invited) Double-pulsed Ultrafast Laser Welding of Glasses Toward Enhancement of Process Efficiency</b> K. Sugioka, S. Wu, and K. Midorikawa RIKEN, Japan	<b>SLPC7-4</b> <b>9:45</b>	<b>(Invited) Enhancement of Fatigue Properties of FSW Joints of A6061 Aluminum Alloy by Laser Peening</b> Y. Sano <sup>1)</sup> , and K. Masaki <sup>2)</sup> <sup>1)</sup> Toshiba Corp., Japan, <sup>2)</sup> Okinawa National College of Technology, Japan
<b>SLPC5-3</b> <b>15:45</b>	<b>Ultrafast Mechanisms in Semiconductor Micro- and Nano-processing by Temporally Shaped Femtosecond Laser Pulses</b> P. A Loukakos, M. Barberoglou, D. Gray, G. D. Tsibidis, E. Stratakis, and C. Fotakis Foundation for Research and Technology - Hellas, Greece ----- Break (16:00-16:30) -----	<b>SLPC7-5</b> <b>10:15</b>	<b>Laser Peening Systems and the Effects of Laser Peening on Aeronautical Metals Sheet</b> S. Zou, and S Gong Beijing Aeronautical Manufacturing Technology Research Institute, China ----- Break (10:30-11:00) -----
<b>16:30-17:45 SLPC6: Ultrashort Pulsed Laser Processing II</b>	Room 313+314	<b>11:00-12:15 SLPC8: Bio-medical and Photonics Applications</b>	Room 313+314
<b>Chairs:</b> P. R. Herman, Univ. of Toronto, Canada, M. Hashida, Kyoto Univ., Japan		<b>Chairs:</b> E. Mottay, Amplitude Systemes, France, K. Sugioka, RIKEN, Japan	
<b>SLPC6-1</b> <b>16:30</b>	<b>(Invited) Ultrafast Laser Processing: a New Route to Innovative Manufacturing</b> J. Choi Department of Laser & Electron Beam Application, Korea Institute of Machinery and Materials, Korea	<b>SLPC8-1</b> <b>11:00</b>	<b>(Invited) Novel Applications by Femtosecond Laser in Electronics and Medical Device Industries</b> C. W. Cheng <sup>1,2)</sup> , C. Y. Lin <sup>2)</sup> , P. H. Wu <sup>2)</sup> , K. P. Chang <sup>2)</sup> , J. B. Horng <sup>2)</sup> , W. T. Wu <sup>3)</sup> , and K. L. Ou <sup>4,5,6,7)</sup> <sup>1)</sup> National Chiao Tung Univ., Taiwan, <sup>2)</sup> Industrial Technology Research Institute, Taiwan, <sup>3)</sup> National Pingtung, Univ. of Science and Technology, Taiwan, <sup>4)</sup> Taipei Medical Univ., Taiwan, <sup>5)</sup> Research Center for Biomedical Devices and Prototyping Production, Taipei Medical Univ., Taiwan, <sup>6)</sup> Research Center for Biomedical Implants and Microsurgery Devices, Taipei Medical Univ., Taiwan, <sup>7)</sup> Taipei Medical Univ.-Shuang Ho Hospital, Taiwan
<b>SLPC6-2</b> <b>17:00</b>	<b>Monolithic Fabrication of Electrofluidic Glass Microchips Based on Femtosecond Laser Direct-write Technique</b> J. Xu, K. Midorikawa, and K. Sugioka RIKEN Center for Advanced Photonics, Japan	<b>SLPC8-2</b> <b>11:30</b>	<b>(Invited) Femtosecond Laser Generated Optically Generated Sub-100 nm Structures for Biomedical and Technical Applications</b> K. Koenig <sup>1)</sup> , and A. Ostendorf <sup>2)</sup> <sup>1)</sup> Saarland Univ., Germany, <sup>2)</sup> Ruhr Univ., Germany
<b>SLPC6-3</b> <b>17:15</b>	<b>Cutting Strengthened Glass Using Bursts of Picosecond Pulses from a MOPA Fiber Laser</b> D. Gay <sup>1)</sup> , L. Desbiens <sup>1)</sup> , S. Lavoie <sup>2)</sup> , and Y. Taillon <sup>1)</sup> <sup>1)</sup> INO, Canada, <sup>2)</sup> Allied Scientific Pro, Canada	<b>SLPC8-3</b> <b>12:00</b>	<b>Femtosecond Laser Integration of High-performance Microoptical Devices into 3D Microchannel for Optofluidic Application</b> D. Wu <sup>1)</sup> , J. Xu <sup>2)</sup> , S. Wu <sup>1)</sup> , K. Midorikawa <sup>1)</sup> , and K. Sugioka <sup>1,2)</sup> <sup>1)</sup> Laser Technology Laboratory, RIKEN, Japan, <sup>2)</sup> RIKEN-SIOM Joint Research Unit, RIKEN, Japan ----- Lunch Break (12:15-13:15) -----
<b>SLPC6-4</b> <b>17:30</b>	<b>Plasma Expansion During Laser Structuring of Metals with ps Pulse Bursts</b> C. Hartmann <sup>1,2)</sup> , and A. Gillner <sup>2)</sup> <sup>1)</sup> Chair for Laser Technology, Technical Univ. Aachen, Germany, <sup>2)</sup> Fraunhofer Institute for Laser Technology ILT, Germany	<b>13:15-14:45 SLPC9: Processing of CFRP</b>	Room 313+314
	<b>Thursday, April 24</b>	<b>Chairs:</b> R. Patel, Spectra Physics, USA, K. Washio, Paradigm Laser Research Ltd., Japan	
<b>8:30-10:45 SLPC7: Additive Manufacturing and Advanced Surface Processing</b>	Room 313+314	<b>SLPC9-1</b> <b>13:15</b>	<b>(Invited) Laser Machining of CFRP Composite – a Comparison of Fibre, Nd:YAG, CO<sub>2</sub>, DPSS and Picosecond Laser Processing</b> Lin Li The Univ. of Manchester, UK
<b>Chairs:</b> R. Poprawe, Fraunhofer Institute for Laser Technology ILT, Germany, H. Nakano, Kinki Univ., Japan		<b>SLPC9-2</b>	<b>Investigations in Wavelength Adapted Laser</b>
<b>SLPC7-1</b> <b>8:30</b>	<b>(Invited) Opportunities and Challenges in Laser 3D Printing</b> B. Gu Bos Photonics, USA		
<b>SLPC7-2</b> <b>9:00</b>	<b>(Invited) Advanced Laser Processing Technology in BAMTRI</b> S. Gong Beijing Aeronautical Manufacturing Technology Research Institute, China		
<b>SLPC7-3</b>	<b>Effect of Defects on Mechanical Properties of</b>		

<b>13:45</b>	<b>Remote Treatment of Fiber Reinforced Polymers</b>	<sup>1)</sup> Servo-Robot Inc., Canada, <sup>2)</sup> Servo-Robot Japan, Japan
	A. Klotzbach <sup>1)</sup> , A. Fürst <sup>1,2)</sup> , J. Hauptmann <sup>1)</sup> , and E. Beyer <sup>1,2)</sup>	
	<sup>1)</sup> Fraunhofer Institute Material and Beam Technology, Germany, <sup>2)</sup> Technische Univ. Dresden, Germany	
<b>SLPC9-3 14:00</b>	<b>Micromachining of Thin CFRP with UV-ps Laser Pulses</b>	<b>SLPC10-5 16:45</b> <b>Freeform Beam Shaping for Industrial Technologies Based on Fiber or Fiber-coupled Lasers</b>
	M. Fujita <sup>1)</sup> , H. Ohkawa <sup>2)</sup> , M. Otsuka <sup>2)</sup> , T. Somekawa <sup>1)</sup> , Y. Maeda <sup>2)</sup> , Y. Orii <sup>3)</sup> , K. Inaba <sup>3)</sup> , G. Okada <sup>3)</sup> , and N. Miyanaga <sup>3)</sup>	A. V. Laskin, and V Laskin AdlOptica GmbH, Germany
	<sup>1)</sup> Institute for Laser Technology, Japan, <sup>2)</sup> Kinki Univ., Japan, <sup>3)</sup> Spectronix Corp., Japan, <sup>4)</sup> Institute of Laser Engineering, Osaka Univ., Japan	
<b>SLPC9-4 14:15</b>	<b>Laser Cutting of CFRP by Q-CW Fiber Laser</b>	<b>17:00-17:15 Closing</b> Room 313+314
	H. Yoshida <sup>1)</sup> , S. Yamazaki <sup>1)</sup> , H. Fukagawa <sup>1)</sup> , T. Tanaka <sup>2)</sup> , T. Imai <sup>2)</sup> , and H. Ogawa <sup>2)</sup>	<b>Closing Remarks</b>
	<sup>1)</sup> Gifu Univ., Japan, <sup>2)</sup> Technological Innovation Center GIFU, Japan	
<b>SLPC9-5 14:30</b>	<b>Influences of Laser Scanning Conditions for CFRP Processing with Fiber Laser</b>	<b>17:00</b> M. Tsukamoto, Osaka Univ., Japan
	K. Takahashi <sup>1)</sup> , M. Tsukamoto <sup>1)</sup> , S. Masuno <sup>1)</sup> , Y. Sato <sup>1)</sup> , M. Matsushita <sup>2)</sup> , K. Furukawa <sup>2)</sup> , H. Yoshida <sup>3)</sup> , K. Tsubakimoto <sup>3)</sup> , H. Fujita <sup>3)</sup> , N. Miyanaga <sup>3)</sup> , T. Yamamura <sup>4)</sup> , M. Ishikawa <sup>4)</sup> , M. Fujita <sup>5)</sup> , H. Niino <sup>6)</sup> , Y. Harada <sup>6)</sup> , M. Muramatsu <sup>6)</sup> , M. Nishino <sup>7)</sup> , T. Kamiya <sup>8)</sup> , O. Matsumoto <sup>8)</sup> , T. Mano <sup>8)</sup> , S. Nakai <sup>8)</sup> , and H. Ogata <sup>8)</sup>	
	<sup>1)</sup> Joining and Welding Research Institute, Osaka Univ., Japan, <sup>2)</sup> Shin Nippon Koki Co., Ltd., Japan, <sup>3)</sup> Institute of Laser Engineering, Osaka Univ., Japan, <sup>4)</sup> Advanced Laser Research Laboratory, Kataoka Corp., Japan, <sup>5)</sup> Institute of Laser Technology, Japan, <sup>6)</sup> Advanced Industrial Science and Technology, Japan, <sup>7)</sup> Mitsubishi Chemical Co., Ltd., Japan, <sup>8)</sup> Advanced Laser and Process Technology Research Association, Japan	
	----- Break (14:45-15:15) -----	
<b>15:15-17:00</b>	<b>SLPC10: Industrial Applications</b>	
		Room 313+314
<b>Chairs:</b> <b>B. Gu</b> , Bos Photonics, USA,		
<b>K. Hirano</b> , Nippon Steel & Sumitomo Metal Corp., Japan		
<b>SLPC10-1 15:15</b>	<b>(Invited) Laser-based Micro-processing for Electronics Industries</b>	
	H. Zhang	
	Electro Scientific Industries, Inc., USA	
<b>SLPC10-2 15:45</b>	<b>(Invited) Laser Processing for Display Glass</b>	
	S. Shimizu	
	Mitsuboshi Diamond Industrial Co., Ltd., Japan	
<b>SLPC10-3 16:15</b>	<b>Laser Drilling with ps Laser and ms Laser in Thermal Barrier Coated Single-Crystal Alloy</b>	
	X. Zhang, R. Sun, W. Zhang, and S. Gong	
	Beijing Aeronautical Manufacturing Technology Research Institute, China	
<b>SLPC10-4 16:30</b>	<b>Smart Laser Tracking, Welding and Monitoring,</b>	
	J. P. Boillot <sup>1)</sup> , R. Simoneau <sup>1)</sup> , J. C. Fontaine <sup>1)</sup> , J. A. Gaboury <sup>1)</sup> , and N. Torii <sup>2)</sup>	